

# DZ2408200L

## Silicon epitaxial planar type

For constant voltage / For surge absorption circuit

Capability of withstanding a high surge type

DZ2W082 in Power type package

### ■ Features

- Excellent rising characteristics of zener current I<sub>Z</sub>
- Low zener operating resistance R<sub>Z</sub>
- Halogen-free / RoHS compliant  
 (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)

### ■ Marking Symbol: JJ

### ■ Packaging

Embossed type (Thermo-compression sealing) : 3 000 pcs / reel (standard)

### ■ Absolute Maximum Ratings Ta = 25 °C

| Parameter  | Symbol           | Rating      | Unit |
|--|------------------|-------------|------|
| Repetitive peak forward current                  | IFRM             | 500         | mA   |
| Forward current                                  | IF               | 400         | mA   |
| Total power dissipation <sup>*1</sup>            | PT               | 2           | W    |
| Non-repetitive reverse power surge <sup>*2</sup> | PZSM             | 100         | W    |
| Electrostatic discharge <sup>*3</sup>            | ESD              | ±30         | kV   |
| Junction temperature                             | T <sub>j</sub>   | 150         | °C   |
| Operating ambient temperature                    | T <sub>opr</sub> | -40 to +85  | °C   |
| Storage temperature                              | T <sub>stg</sub> | -55 to +150 | °C   |

Note: \*1 Mounted on ceramics print circuit board.

Board size: 50 mm × 50 mm

Board thickness: 0.8 mm

Soldering size: 2 mm × 2 mm

\*2 t = 0.1ms

\*3 Test method:IEC61000\_4\_2(C = 150 pF,R = 330 Ω, Contact discharge:10 times)

### ■ Electrical Characteristics Ta = 25 °C ± 3 °C

| Parameter  | Symbol | Conditions  | Min  | Typ  | Max  | Unit  |
|--|--------|-------------|------|------|------|-------|
| Forward voltage  | VF     | IF = 200 mA |      |      | 1.2  | V     |
| Zener voltage <sup>*1, *2</sup>                        | VZ     | IZ = 10 mA  | 7.79 | 8.20 | 8.61 | V     |
| Zener operating resistance                             | RZ     | IZ = 10 mA  |      |      | 30   | Ω     |
| Reverse current  | IR     | VR = 4.0 V  |      |      | 10   | μA    |
| Temperature coefficient of zener voltage <sup>*3</sup> | SZ     | IZ = 10 mA  |      | 4.7  |      | mV/°C |

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.

2. Absolute frequency of input and output is 5 MHz.

3. \*1 The temperature must be controlled 25°C for VZ measurement.

VZ value measured at other temperature must be adjusted to VZ (25°C)

\*2 VZ guaranteed 20 ms after current flow.

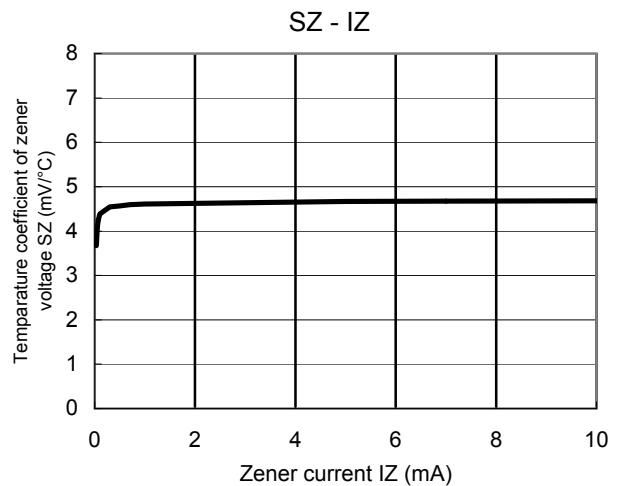
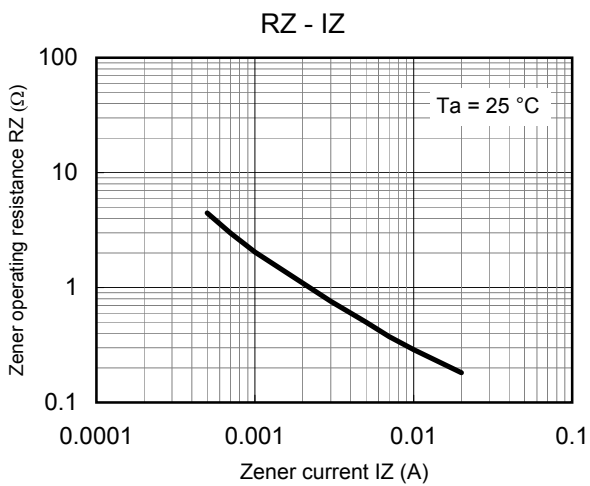
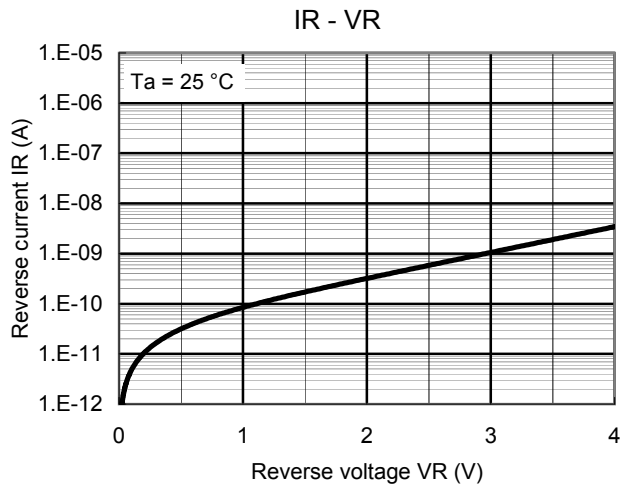
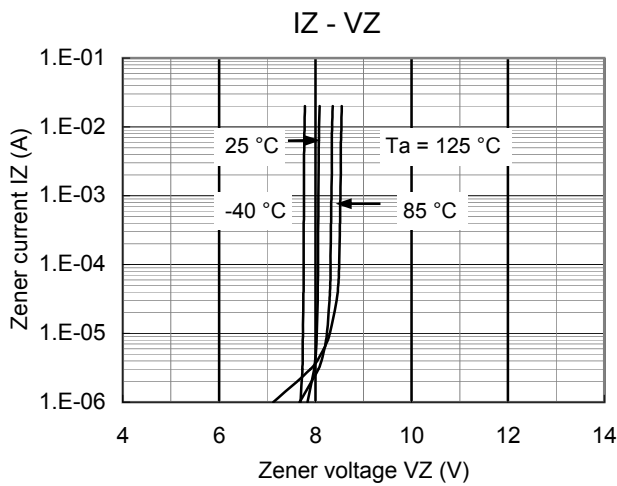
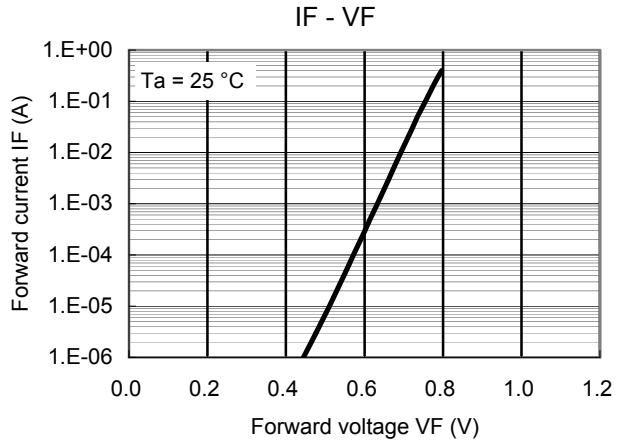
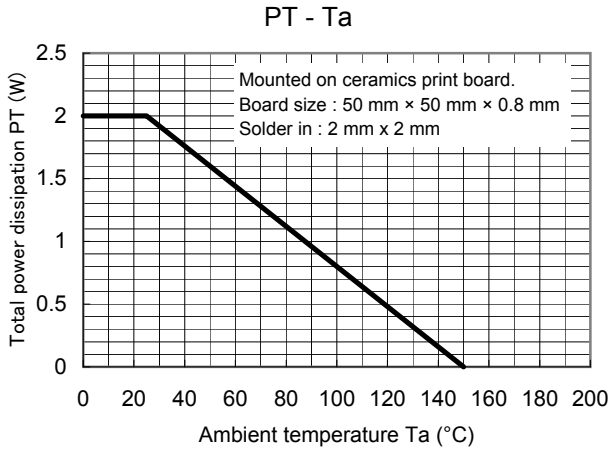
\*3 T<sub>j</sub> = 25°C to 150°C



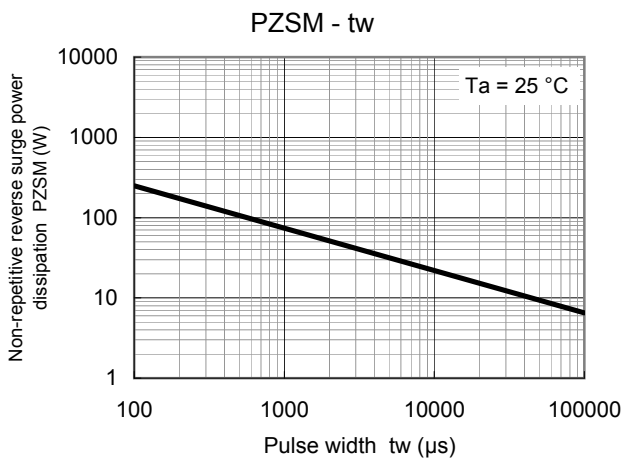
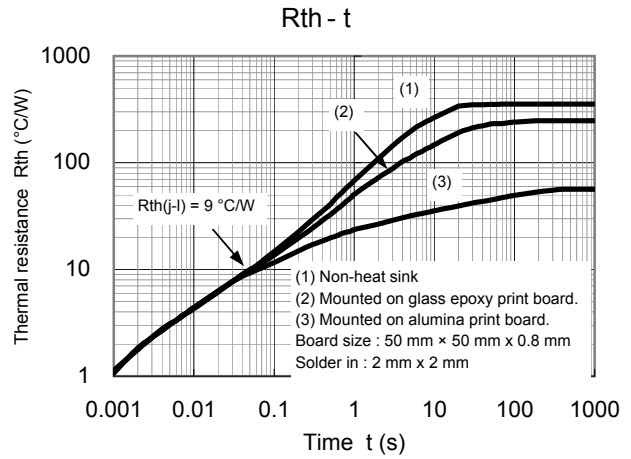
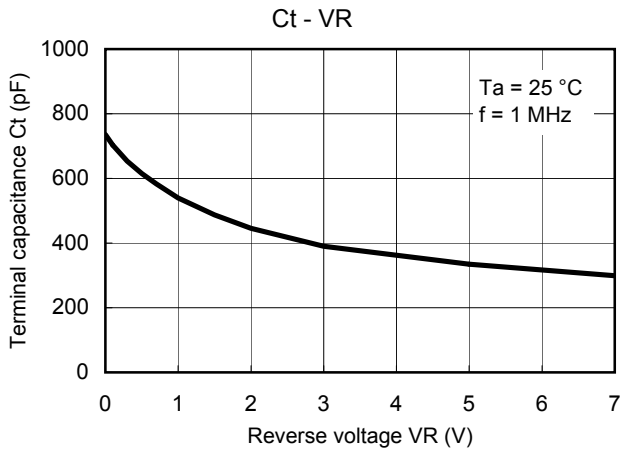
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|-----------|--------------|
| Panasonic | TMiniP2-F2-B |
| JEITA     | SC-110A      |
| Code      | —            |



Technical Data ( reference )

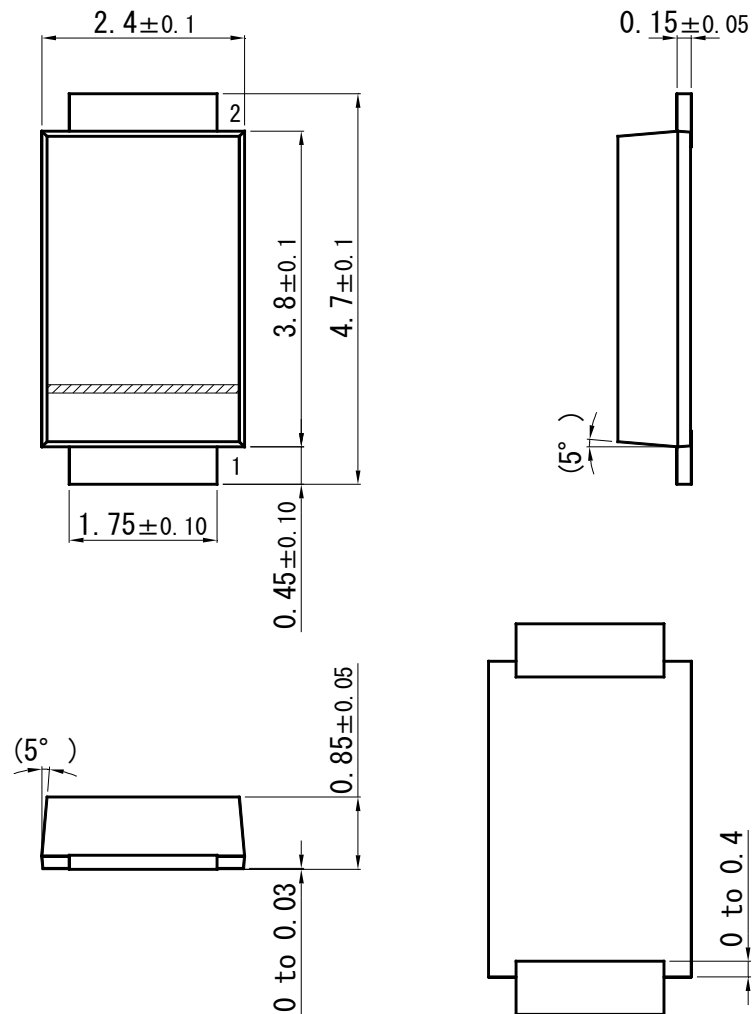


Technical Data ( reference )



TMiniP2-F2-B

Unit: mm



■ Land Pattern (Reference) (Unit: mm)



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